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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Scott Fuller et al.
Applicants

January 15, 2004
Filing Date

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Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
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	4,357,416	11/02/82	Fan	430	302	
	5,234,990	08/10/93	Flaim et al. *	524	609	
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	5,554,485	09/10/96	Dichiara et al. *	430	271.1	
	5,723,237	03/03/98	Kobayashi et al. *	430	30	
	5,879,853	03/09/99	Azuma *	430	166	
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	5,935,768	08/10/99	Biche et al. **	430	401	
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	6,048,672	04/11/00	Cameron et al.	430	327	
NM	6,110,638	08/29/00	Masuda et al. **	430	270.1	

Examiner: Nicole Barreca Date Considered: 9/25/04

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* Cited in a Search Report in corresponding PCT Application No. PCT/US02/22609.

** Cited during the prosecution of the parent application, U.S. Application Serial No. 09/912,116.

2/18/04

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WB	6,156,479	12/05/00	Meador et al.	430	270.1	
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	2002/0012876 A1	01/31/02	Angelopolous et al. *	430	271.1	08/17/01
	2002/0182514 A1	12/05/02	Montgomery et al. **	430	5	05/03/01

Examiner: Nicole Barreca Date Considered: 8/25/04

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	EP 0905565	03/31/99	Lu et al. *	G03F	7/09	
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[illegible]	WO 0054105	09/14/00	Foster et al.	G03C	1/492	

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